

Material Declaration Report

Package Type:	LQFP 128 (14*14mm)
Pericom Package Code:	FD128
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	671.0000
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	2011/12/5

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	402.600	GTK	Epoxy Resin	Trade secret	8.00	32.2080
			Phenol Resin	Trade secret	6.00	24.1560
			Carbon Black	1333-86-4	0.50	2.0130
			Silica fused	60676-86-0	75.00	301.9500
			Silica fused	7631-86-9	10.00	40.2600
			Silica crystalline	14808-60-7	0.50	2.0130
LEADFRAME	214.720		Copper	7440-50-8	94.3	202.4810
			Nickle (Ni)	7440-02-0	3.2	6.8710
			Silicon (Si)	7440-21-3	0.8	1.7178
			Magnesium (Mg)	7739-95-4	0.2	0.4294
			Silver (Ag)	7440-22-4	1.5	3.2208
SILICON DIE	32.342		Silicon (Si)	7440-21-3	99.19	32.0809
			Non-hazardous Metal	Proprietary	0.81	0.2613
DIE ATTACH EPOXY	0.537		Silver	7440-22-4	72.00	0.3866
			Epoxy resin A	9003-36-5	5.00	0.0269
			Epoxy resin B	Trade secret	6.00	0.0322
			Diluent A	Trade secret	6.00	0.0322
			Diluent B	Trade secret	5.00	0.0269
			Hardener	Trade secret	5.00	0.0269
			Dicyandiamide	461-58-5	0.30	0.0016
			Organic peroxide	Trade secret	0.70	0.0038
WIRE BOND	0.671		Gold	7440-57-5	99.99	0.6709
			Impurity	-	0.01	0.0001
PLATING	20.130		pure tin	7440-31-5	99.99	20.1280
			Impurity	-	0.01	0.0020

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.